



# Solid State Devices, Inc.

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# SGF48N10M SGF48N10S1

## 48 AMP GaN POWER FET Enhancement Mode 100 VOLTS, 8 – 10 mΩ

### Designer's Data Sheet

**Part Number/Ordering Information<sup>1/</sup>**

**SGF48N10**                     

L Screening<sup>2/</sup>  
       = Not Screened  
   TX = TX Level  
   TXV = TXV Level  
   S = S Level

**Lead Bend Options  
(TO-254 only)**  
       = Straight Leads  
   UB = Up Bend  
   DB = Down Bend

**Package**  
   M = TO-254  
   S1 = SMD1

**FEATURES:**

- 4<sup>th</sup> Generation Gallium Nitride Technology
- Exceptionally Low R<sub>DS(ON)</sub>
- Low Q<sub>G</sub> Simplifies Gate Drive Circuit
- Very Fast Switching for High-Freq. Applications
- Low Thermal Resistance
- Hermetically Sealed Package
- Available in Hermetically Sealed, Chip-Scale Package (SMG.3-1)
- TX, TXV, and S-Level Screening Available<sup>2/</sup>

**APPLICATIONS:**

- High Efficiency DC-DC / PoL Converters
- Motor Controller
- Robotics/Automation
- Military and Aerospace

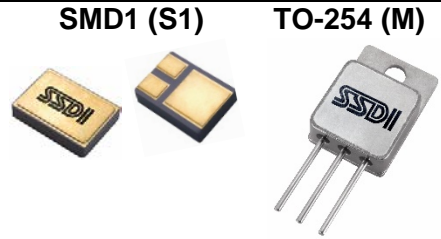
**BENEFITS:**

- GaN Transistor offers superior advantages over Si based MOSFET: zero Q<sub>RR</sub>, low gate charge, low R<sub>DS(ON)</sub>, fast switching speed and low temperature coefficient
- Benefits circuit designer through higher efficiency, lower cross-over losses and On-state losses
- Eliminates the need to add free-wheeling diode

Maximum Ratings <sup>3/</sup>	Symbol	Value	Units
Continuous Drain - Source Voltage	V <sub>DSS</sub>	100	V
Gate – Source Voltage	V <sub>GS</sub>	+6 -4	V
Continuous Drain Current	I <sub>D1</sub>	48	A
Pulsed Drain Current T <sub>op</sub> / P <sub>width</sub> limited	I <sub>D2</sub>	340	A
Total Power Dissipation	P <sub>D</sub>	25	W
Operating & Storage Temperature	T <sub>OP</sub> & T <sub>STG</sub>	-55 to +150	°C
Thermal Resistance Junction to Case	R <sub>θJC</sub>	5	°C/W

**NOTES:**

- 1/ For ordering information, price, operating curves, and availability- contact factory.
- 2/ Screening based on MIL-PRF-19500. Screening flows available on request.
- 3/ Unless otherwise specified, all electrical characteristics @ 25°C.
- 4/ Pulse Test, P<sub>w</sub> = 300 μs, D.C. = 2%.
- 5/ Attach device with low temperature solder such as Sn63 with peak reflow temperature of 215°C and maximum dwell time of 30 sec.





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Electrical Characteristics <sup>3/</sup>	Symbol	Min	Typ	Max	Units
<b>Drain to Source Breakdown Voltage</b> $V_{GS} = 0\text{ V}, I_D = 0.8\text{ mA}$	$BV_{DSS}$	100	-	-	V
<b>Gate to Source Leakage</b> $V_{GS} = +5\text{ V}$ $V_{GS} = -4\text{ V}$	$I_{GSS}$	-	1 0.1	9 0.6	mA
<b>Zero Gate Voltage Drain Current</b> $V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}, T_J = 25^\circ\text{C}$	$I_{DSS}$	-	0.1	0.6	mA
<b>Gate Threshold Voltage</b> $V_{DS} = V_{GS}, I_D = 11\text{ mA}, T_J = 25^\circ\text{C}$	$V_{GS(th)}$	0.8	1.4	2.5	V
<b>Drain to Source On State Resistance<sup>4/</sup></b> $V_{GS} = 5\text{ V}, I_D = 30\text{ A}, T_J = 25^\circ\text{C}$	$R_{DS(on)}$	-	-	8 10	m $\Omega$
<b>Source to Drain Forward Voltage<sup>4/</sup></b> $I_F = 0.5\text{ A}, V_{GS} = 0\text{ V}$	$V_{SD}$	-	1.8	-	V
<b>Total Gate Charge</b> $V_{GS} = 5\text{ V}, V_{DS} = 50\text{ V}, I_D = 30\text{ A}$	$Q_G$	-	12	15	nC
<b>Gate to Source Charge</b> <b>Gate to Drain Charge</b> <b>Gate Threshold Charge</b>	$Q_{GS}$ $Q_{GD}$ $Q_{GTH}$	-	3.1 2 2.3	10 4 4.6	nC
<b>Input Capacitance</b> <b>Output Capacitance</b> <b>Reverse Transfer Capacitance</b>	$C_{ISS}$ $C_{OSS}$ $C_{RSS}$	-	1270 800 14	1530 1200 -	pF
<b>Output Charge</b> $V_{GS} = 0\text{ V}, V_{DS} = 50\text{ V}$	$Q_{OSS}$	-	66	100	nC
<b>Source to Drain Recovery Charge</b>	$Q_{RR}$	-	0	-	$\mu\text{C}$
<b>Gate Resistance</b>	$R_G$	-	0.4	-	$\Omega$

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4/ Pulse Test,  $P_W = 300\ \mu\text{s}$ , D.C. = 2%.

5/ Attach device with low temperature solder such as Sn63 with peak reflow temperature of 215°C and maximum dwell time of 30 sec.

**NOTE:** All specifications are subject to change without notification.  
 SCD's for these devices should be reviewed by SSDI prior to release.

**DATA SHEET #: FT0070C**

**DOC**



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**SGF48N10M**  
**SGF48N10S1**

**Package Outlines:**

<p style="text-align: center;"><b>SMD1 (S1)</b></p> <p>Dimensions (inches): .150, .130, .055, .045, .145, .135, .035 MIN, .035, .025 MIN, .162, .152, .630, .620, .420, .410, .020, .010, .042, .032, .380, .370, .455, .445</p>	<p style="text-align: center;"><b>TO-254 (M)</b></p> <p>Dimensions (inches): <math>\varnothing .150</math>, .139, .800, .790, .750, .500, .155, .145, .545, .535, .305, .295, .685, .665, .260, .240, .155, .140, .050, .040, .170 MIN, 3x <math>\varnothing .045</math>, 3x <math>\varnothing .035</math>, 3x .190, .150, 3x .190, .150</p> <p><b>SUFFIX: M</b></p> <p><b>SUFFIX: MDB</b>     <b>SUFFIX: MUB</b></p>																		
<p><b>AVAILABLE PART NUMBERS:</b>  <b>SMD1:</b> SGF48N10S1  <b>TO-254:</b> SGF48N10M, SGF48N10MDB, SGF48N10MUB</p> <p><i>Dimensions in inches</i></p>	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th colspan="3" style="text-align: center;"><b>PIN ASSIGNMENT</b></th> </tr> <tr> <th></th> <th style="text-align: center;"><b>SMD1</b></th> <th style="text-align: center;"><b>TO-254</b></th> </tr> </thead> <tbody> <tr> <td>Source</td> <td style="text-align: center;">3</td> <td style="text-align: center;">2</td> </tr> <tr> <td>Drain</td> <td style="text-align: center;">2</td> <td style="text-align: center;">1</td> </tr> <tr> <td>Gate</td> <td style="text-align: center;">1</td> <td style="text-align: center;">3</td> </tr> <tr> <td>Substrate</td> <td style="text-align: center;">*</td> <td style="text-align: center;">*</td> </tr> </tbody> </table> <p style="text-align: center;">* Substrate internally tied to Source</p>	<b>PIN ASSIGNMENT</b>				<b>SMD1</b>	<b>TO-254</b>	Source	3	2	Drain	2	1	Gate	1	3	Substrate	*	*
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